



Material Content Data Sheet



Sales Product Name	TLE8386EL			Issued	28. August 2013			
MA#	MA000971506							
Package	PG-SSOP-14-3			Weight*	83.06 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.030	2.44	2.44	24439	24439
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8296	
wire	non noble metal	copper	7440-50-8	27.978	33.68	34.56	336844	345659
	noble metal	gold	7440-57-5	0.199	0.24	0.24	2395	2395
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
	plastics	epoxy resin	-	4.570	5.50		55017	
	inorganic material	silicondioxide	60676-86-0	45.001	54.19	59.81	541799	598012
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11752	11752
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9242	9242
glue	plastics	epoxy resin	-	0.177	0.21		2125	
	noble metal	silver	7440-22-4	0.530	0.64	0.85	6376	8501
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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